

DIPLOMA EXAMINATION IN ENGINEERING/TECHNOLOGY/
MANAGEMENT/COMMERCIAL PRACTICE — APRIL, 2018

COMPUTER SYSTEM HARDWARE

[Time : 3 hours

(Maximum marks : 100)

PART — A

(Maximum marks : 10)

Marks

I Answer *all* questions in one or two sentences. Each question carries 2 marks.

1. Name chipset built in controllers.
2. Define the term AMR.
3. Specify the use of sector interleave.
4. List any two keyboard connectors.
5. State the need for partitioning hard disk.

(5×2 = 10)

PART — B

(Maximum marks : 30)

II Answer any *five* of the following questions. Each question carries 6 marks.

1. Explain about cache memory.
2. Write the power requirements in a PC.
3. Explain memory parity and ECC.
4. Explain any three BIOS ROM.
5. Compare passive and active matrix.
6. Describe USB interface.
7. Explain any three type of viruses.

(5×6 = 30)

PART — C

(Maximum marks : 60)

(Answer *one* full question from each unit. Each full question carries 15 marks.)

UNIT — I

- III (a) Explain the working of SMPS with block diagram. 9
 (b) List the voltage signals and color code from ATX SMPS. 6

OR

- IV (a) Discuss the Mother board components :
 (i) BIOS (ii) Chipset (iii) PCI Express slot 9
 (b) Explain any two mother board form factors. 6

UNIT — II

- V (a) Describe the construction of the hard disk. 9
 (b) Explain any three HDD interfaces. 6

OR

- VI (a) Explain any three types of video RAMs. 9
 (b) Compare SRAM and DRAM. 6

UNIT — III

- VII (a) Explain the working of LCD Monitors. 9
 (b) List any six video display standard. 6

OR

- VIII (a) Explain the working of laser printers. 9
 (b) Describe optical mouse. 6

UNIT — IV

- IX (a) State the need for formatting. Discuss high level and low level formatting. 9
 (b) Write any three data recovery tools. 6

OR

- X (a) List the components required for system assembling. 6
 (b) Explain system assembling procedure. 9